GaAs N Channel Dual Gate MES FET UHF RF Amplifier



ADE-208-472 A 2nd. Edition

#### Features

- Capable of low voltage operation ( $V_{DS} = 1.5$  to 3 V)
- Excellent low noise characteristics (NF = 1.25 dB typ. at f = 900 MHz)
- High power gain (PG = 21.0 dB typ. at f = 900 MHz)

#### Outline

CMPAK-4	3	1. Source 2. Gate1 3. Gate2 4. Drain	



## **Absolute Maximum Ratings** (Ta = $25^{\circ}$ C)

Item	Symbol	Ratings	Unit	
Drain to source voltage	V <sub>DS</sub>	6	V	
Gate 1 to source voltage	V <sub>G1S</sub>	-4	V	
Gate 2 to source voltage	V <sub>G2S</sub>	-4	V	
Drain current	I <sub>D</sub>	18	mA	
Channel power dissipation	Pch	100	mW	
Channel temperature	Tch	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

## **Electrical Characteristics** (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Gate 1 to cutoff current	I <sub>G1SS</sub>	—	—	-20	μA	$V_{\text{G1S}} = -4 \text{ V}$ $V_{\text{G2S}} = V_{\text{DS}} = 0$
Gate 2 to cutoff current	I <sub>G2SS</sub>	—	—	-20	μA	$V_{G2S} = -4 V$ $V_{G1S} = V_{DS} = 0$
Gate 1 to source cutoff voltage	$V_{\text{G1S(off)}}$	-0.2	—	-1.5	V	$V_{DS} = 3 V, V_{G2S} = 0$ $I_{D} = 100 \ \mu A$
Gate 2 to source cutoff voltage	$V_{\text{G2S(off)}}$	-0.2	—	-1.5	V	$V_{DS} = 3 V, V_{G1S} = 0$ $I_{D} = 100 \ \mu A$
Zero gate voltege drain current	I <sub>DSS</sub>	25	40	60	mA	$V_{DS} = 3 V, V_{G1S} = 0$ $V_{G2S} = 0$
Forward transfer admittance	y <sub>fs</sub>	30	40	—	mS	$V_{DS} = 3 V, V_{G2S} = 0$ $I_{D} = 5 mA, f = 1 kHz$
Power gain	PG	18	21	_	dB	$V_{DS} = 3 V, V_{G2S} = 0$
Noise figure	NF	_	1.25	1.5	dB	$I_{D} = 5 \text{ mA}, \text{ f} = 900 \text{ MHz}$
Power gain	PG	_	20	_	dB	$V_{\rm DS} = 1.5 \text{ V}, V_{\rm G2S} = 0$
Noise figure	NF	_	1.3	_	dB	$I_{D} = 3 \text{ mA}, \text{ f} = 900 \text{ MHz}$

Note: Marking is "XV-"

#### **Main Characteristics**





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Freq.	S11		S21		S12		S22	
(MHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
100	0.999	-2.8	3.29	176.7	0.00167	95.2	0.963	-0.9
200	0.997	-5.9	3.27	173.1	0.00302	89.0	0.963	-2.2
300	0.995	-9.4	3.29	169.0	0.00394	80.5	0.961	-3.5
400	0.992	-12.3	3.26	165.8	0.00506	83.7	0.959	-5.0
500	0.981	-15.2	3.23	161.9	0.00703	80.8	0.957	-6.3
600	0.968	-18.9	3.22	158.3	0.00797	78.1	0.955	-8.0
700	0.956	-21.8	3.20	154.4	0.00911	76.9	0.953	-9.2
800	0.949	-24.5	3.15	151.3	0.0104	77.1	0.949	-10.6
900	0.935	-27.6	3.14	147.4	0.0114	73.2	0.946	-12.0
1000	0.922	-30.7	3.12	143.7	0.0123	72.1	0.942	-13.5
1100	0.912	-33.5	3.06	140.3	0.0137	71.9	0.939	-14.7
1200	0.895	-36.2	3.03	136.7	0.0139	70.8	0.935	-16.0
1300	0.873	-38.7	2.97	133.3	0.0150	68.5	0.931	-17.3
1400	0.860	-41.4	2.93	130.1	0.0161	68.5	0.926	-18.6
1500	0.838	-43.8	2.89	126.9	0.0162	67.2	0.922	-20.2
1600	0.822	-45.6	2.85	123.6	0.0171	66.6	0.918	-21.5
1700	0.807	-48.3	2.83	120.5	0.0178	67.2	0.913	-22.7
1800	0.787	-50.7	2.79	117.4	0.0185	66.0	0.909	-23.8
1900	0.767	-52.4	2.74	114.4	0.0186	64.3	0.905	-25.5
2000	0.756	-55.0	2.69	110.9	0.0190	63.7	0.901	-26.6

 $\label{eq:sparameter} \textbf{Sparameter}~(V_{\rm DS}=3~V,~V_{\rm G2S}=0,~I_{\rm D}=5~mA,~Zo=50~~)$ 



## **Package Dimentions**

Unit: mm



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